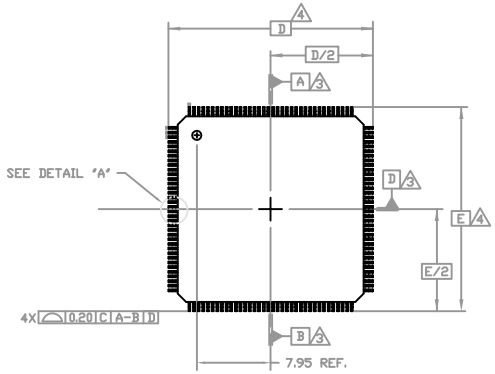
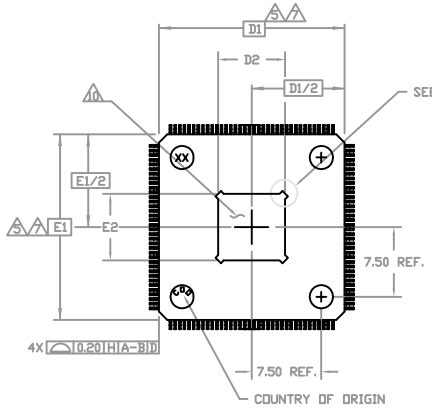
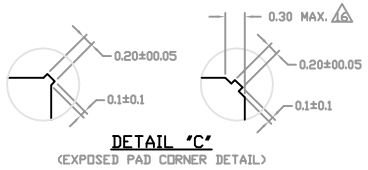
REVISION HISTORY				
REV	DESCRIPTION	DATE	DRAWNED	RELEASED
00	INITIAL RELEASE PER DCN #A38334. (ENG-158-HE BECOMES 35809/00)	07/12 1994	Y.M.K.	Y.M.K.
01	REVISED PER DCN #022203.	03/17 1995	Y.M.K.	Y.M.K.
02	REVISED PER DCN #024559.	10/09 1996	M.P.	M.P.
03	REVISED PER DCN #A50215 ADD EJECTOR PINS PER PRODUCT MANAGER'S REQ.	12/13 2000	CHOSH	CHOSH
04	REVISED PER DCN #A51989 ADDED ePAD OPTION	08/12 2001	CHOSH	CHOSH



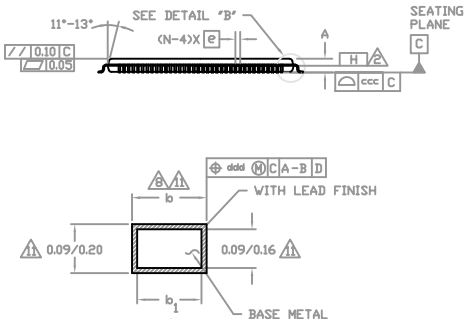
TOP VIEW

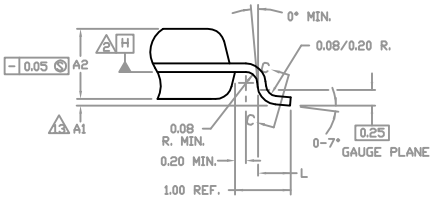


BOTTOM VIEW

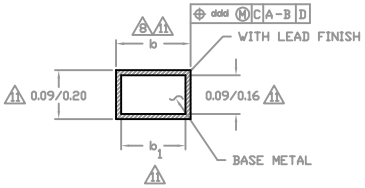


DETAIL "C"
(EXPOSED PAD CORNER DETAIL)



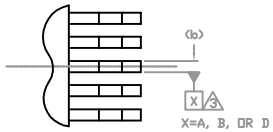


DETAIL "B"

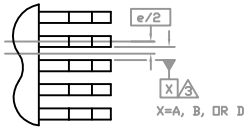


SECTION C-C

ODD LEAD SIDES



EVEN LEAD SIDES



DETAIL "A"

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

DECIMAL: X.X ±, X.XX ±, X.XXX ±
ANGULAR: ±1°

INTERPRET DIM AND TOL PER ASME Y14.5M - 1994

MATERIAL: SEE CHART ABOVE
FINISH: SEE CHART ABOVE

PRINTING IS SCALED TO FIT DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS		DATE
DRAWN	Y JANG	07/12 1994
CHECKED	CK PARK	07/12 1994
APPROVED	BH AHN	07/12 1994
RELEASED	SOKANG	08/12 2001

Amkor Technology, Inc.
Chandler, Arizona, USA
Anam Semiconductor, Inc.,
Seoul, Korea
Amkor Technology Philippines, Inc.
Manila, Philippines

Amkor Technology / ANAM Semiconductor

TITLE: PACKAGE OUTLINE, TQFP, 20 X 20 MM BODY, 1.00/0.10 MM FORM, 1.00 mm THICK (OPTIONAL ePAD)

SIZE: A3 | DWG NUMBER: 35809 | REV: 04

SCALE: 3.5:1 | CUSTOMER DWG: XXXX | SHEET: 1 OF 2

FORM NO. MDFORM3J.DWG